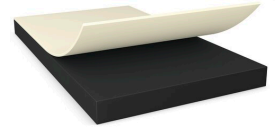




58701

제품 정보



25µm x-linkable polyurethane black HAF mounting tape

제품 설명

tesa® XPU 58701 is a reactive mounting tape offering high bonding strength and elasticity after curing. This black double-sided tape has no backing. It is protected by a PE-coated paper liner. tesa® XPU 58701 is free of halogen according to IEC 61249-2-21 and compliant with current RoHS directive. At room temperature tesa® XPU 58701 is not tacky. It is activated by heat and pressure applied during the assembly process.

특성

- Extremely high bonding performance and reliability, even on thin design gaps
- Excellent shock resistance
- Extremely low oozing ratio
- Black design

Applications

tesa® XPU 58701 is especially recommended for structural bonding of various substrates inside electronic devices:

- Bonding of plastics
- Bonding of metals
- Bonding of electronic components

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

제품 구조

• 기재 소재	없음	• 이형지 종류	PE 코팅된 직물
• 점착제 종류	crosslinkable polyurethane	• 총두께	25 µm

속성 / 성능 값

- 점착력 (푸쉬 아웃) 1.5 N/mm²

추가정보

Technical recommendations:

tesa® XPU 58701 is not self-adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

Pre-lamination

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제품 정보

추가정보

During pre-lamination, laminate the adhesive tape onto the first component.

Setting:

- Temperature¹ 55-65 °C
- Pressure² 3 bar
- Time 5 – 20 s

Short-time exposure to 65 °C bond line temperature during pre-lamination does not affect the final bonding potential.

Bonding

Remove the liner from tape after the pre-lamination step.

Position the second component. Apply temperature and pressure for the bonding time to reach sufficient bonding strength.

PC/PC:

Setting:

- Temperature¹ 80 – 140 °C
- Pressure² 5 bar
- Time 10 – 120 s

AL/PC:

Setting:

- Temperature¹ 110 – 190 °C
- Pressure² 5 bar
- Time 20 – 120 s

Short cycle times can be achieved at high bond line temperatures. For activation at low temperatures, increase the heat-press time. To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours.

Bonding strength values were obtained under standard laboratory conditions.

PC/PC: bonding conditions: temperature = 110 °C (120 °C jig); pressure = 5 bar; time = 60 sec

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Storage: tesa® recommends storage in original packaging in cool and dry conditions.

'Pre-lamination' and 'Bonding' temperature refer to the data that is measured in the bond line.

'Pre-lamination' and 'Bonding' pressure refer to the force that is transferred from jig surface directly to the bonding area.

공지사항

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또는 상업성과 관련한 어떠한 암묵적인 보증도 포함하지 않습니다. 사용자는 제품을 사용하기 전에 적용부위에 적합한지를 검토하시기 바라며, 기타 문의사항이 있으시면 저희 직원에게 문의 바랍니다



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